MAS3132DG

Silicon epitaxial planar type

For switching circuits

■ Features

- Two elements are contained in one package, allowing highdensity mounting
- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	80	V
Maximum peak reverse voltage		V_{RM}	80	V
Forward current	Single	I_F	100	mA
	Double		150	
Peak forward current	Single	I_{FM}	225	mA
	Double		340	
Non-repetitive peak	Single	I_{FSM}	500	mA
forward surge current *	Double		750	
Junction temperature		T _j	150	°C
Storage temperature		T_{stg}	-55 to +150	°C

■ Package

- Code
 - SSSMini3-F2
- Pin Name
 - 1: Cathode 1
 - 2: Cathode 2
 - 3: Anode 1, 2
- Marking Symbol: MO

■ Internal Connection

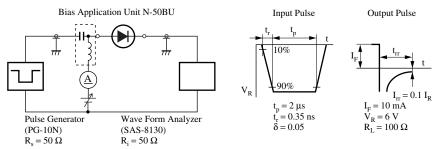


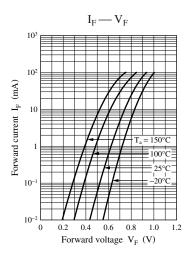
Note) *: t = 1 s

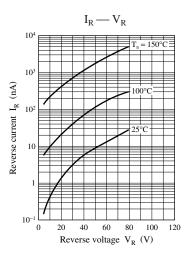
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

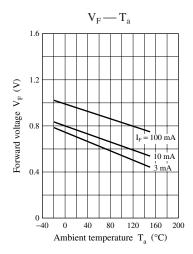
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	V_R	$I_R = 100 \mu A$	80			V
Reverse current	I_R	V _R = 75 V			100	nA
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$			15	pF
Reverse recovery time *	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
		$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$				

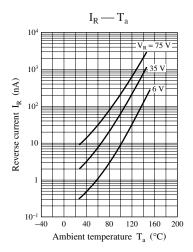
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.
 - 2. Absolute frequency of input and output is 100 MHz.
 - 3. *: t_{rr} measurement circuit

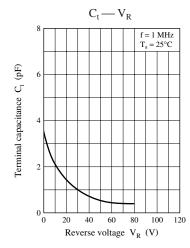


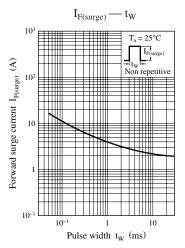






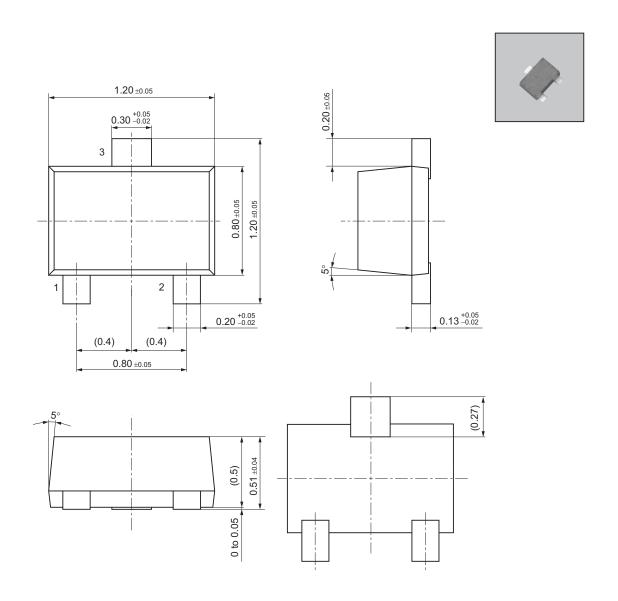






SSSMini3-F2

Unit: mm



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